JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD

SMBG Plastic-Encapsulate Diodes

SS56L Schottky Rectifier Diode

Features

- $I_{F(AV)}$ 5A
- V_{RRM} 60V
- High surge current capability
- Polarity: Color band denotes cathode
- Low peak forward voltage

SMBG





Applications

- Rectifier

Marking

- SS56L:SS56L

Limiting Values(Absolute Maximum Rating)

Item	Symbol	Unit	Test Conditions	SS56L
Repetitive Peak Reverse Voltage	V_{RRM}	V		60
Maximum RMS Voltage	V_{RMS}	V		42
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load	5.0
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave, 1 cycle, Ta=25℃	120
Junction Temperature	T_J	℃		-55 ~ +150
Storage Temperature	T_{STG}	℃		-55 ~ +150

Electrical Characteristics (T=25℃ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		SS56L
Peak Forward Voltage	V_F	V	I_F=5.0A	Ta=25℃	0.50
Peak Reverse Current	I_{RRM1}	mA	$V_{RM}=V_{RRM}$	Ta=25℃	0.3
	I_{RRM2}			Ta=100℃	50
Thermal Resistance(Typical)	$R_{\theta J-A}$	℃/W	Between junction and ambient		55
	$R_{\theta J-L}$		Between junction and lead		13
Juction Capacitance (Typical)	Cj	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C		400

Notes:

Thermal resistance from junction to ambient and from juction to lead mounted on FR4 PCB double sided copper mini pad

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

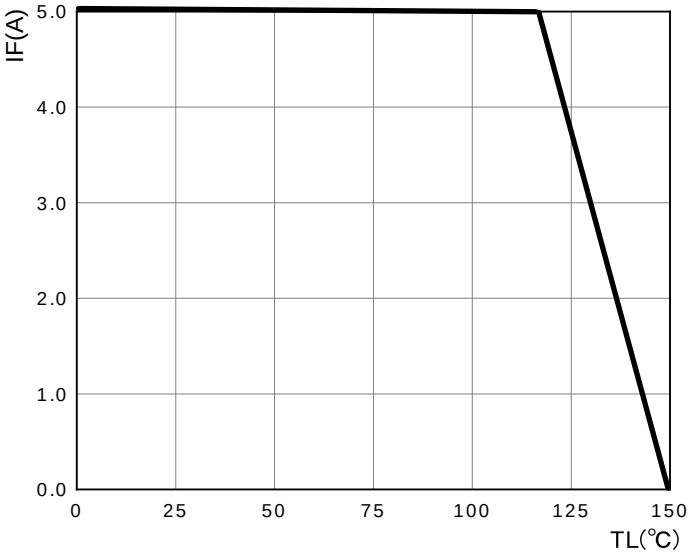


FIG 2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

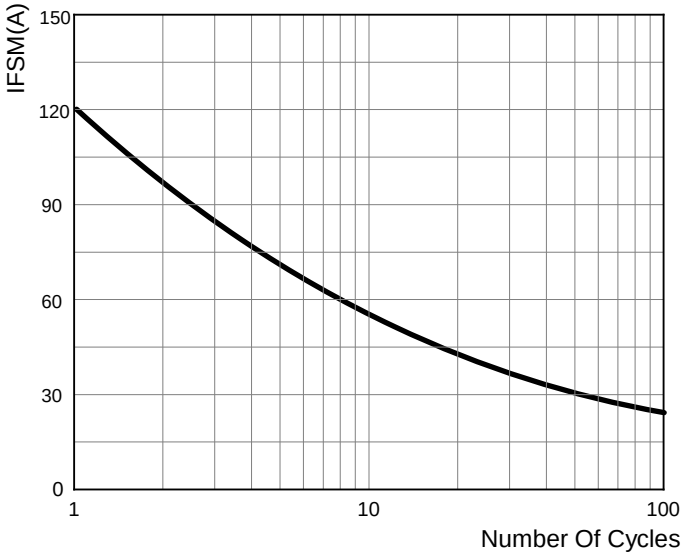


FIG.3: TYPICAL FORWARD CHARACTERISTICS

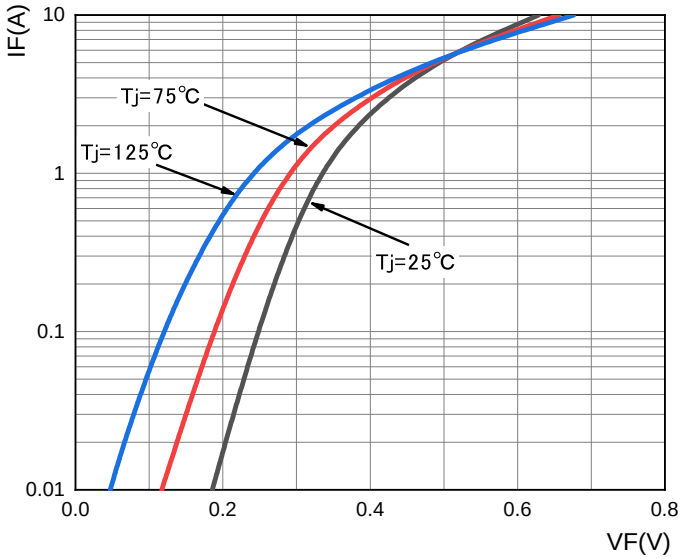
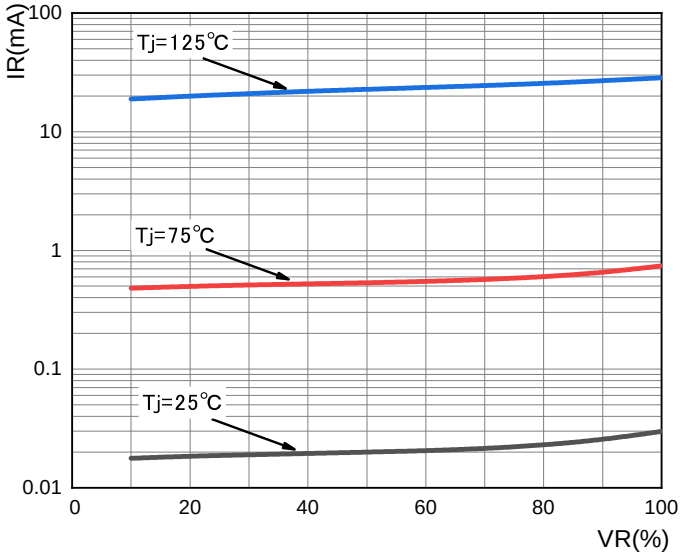
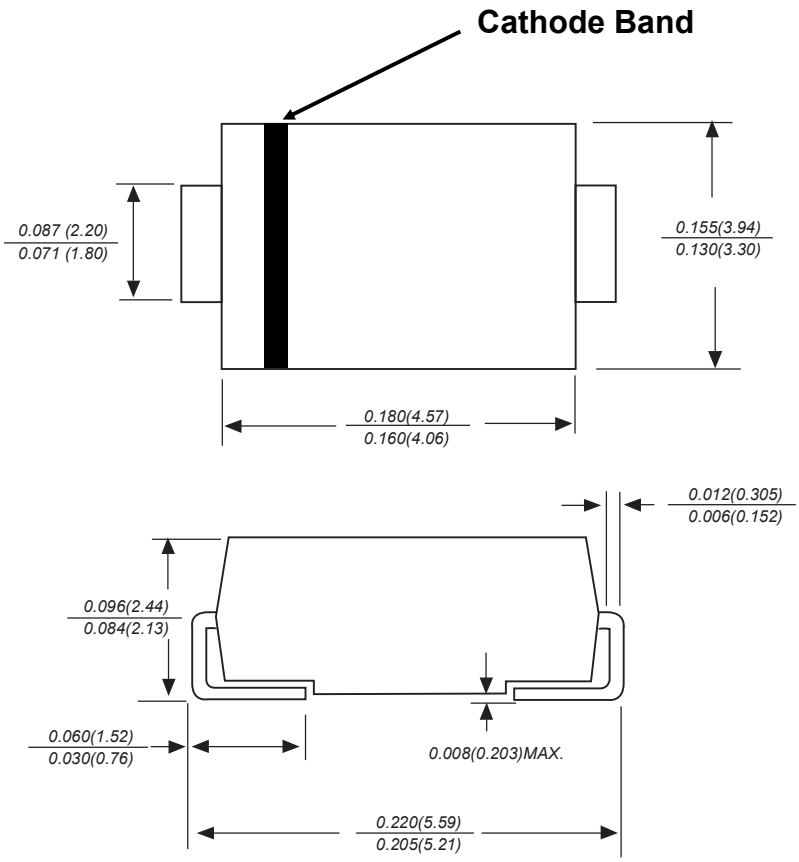


FIG.4: TYPICAL REVERSE CHARACTERISTICS

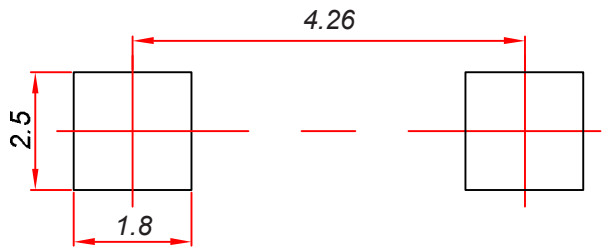


SMBG Package Outline Dimensions



Dimensions in inches and (millimeters)

SMBG Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

NOTICE
JSCJ reserves the right to make modifications,enhancements,improvements,corrections or other changes without further notice to any product herein.JSCJ does not assume any liability arising out of the application or use of any product described herein.

Reel Taping Specifications For Surface Mount Devices-SMBG

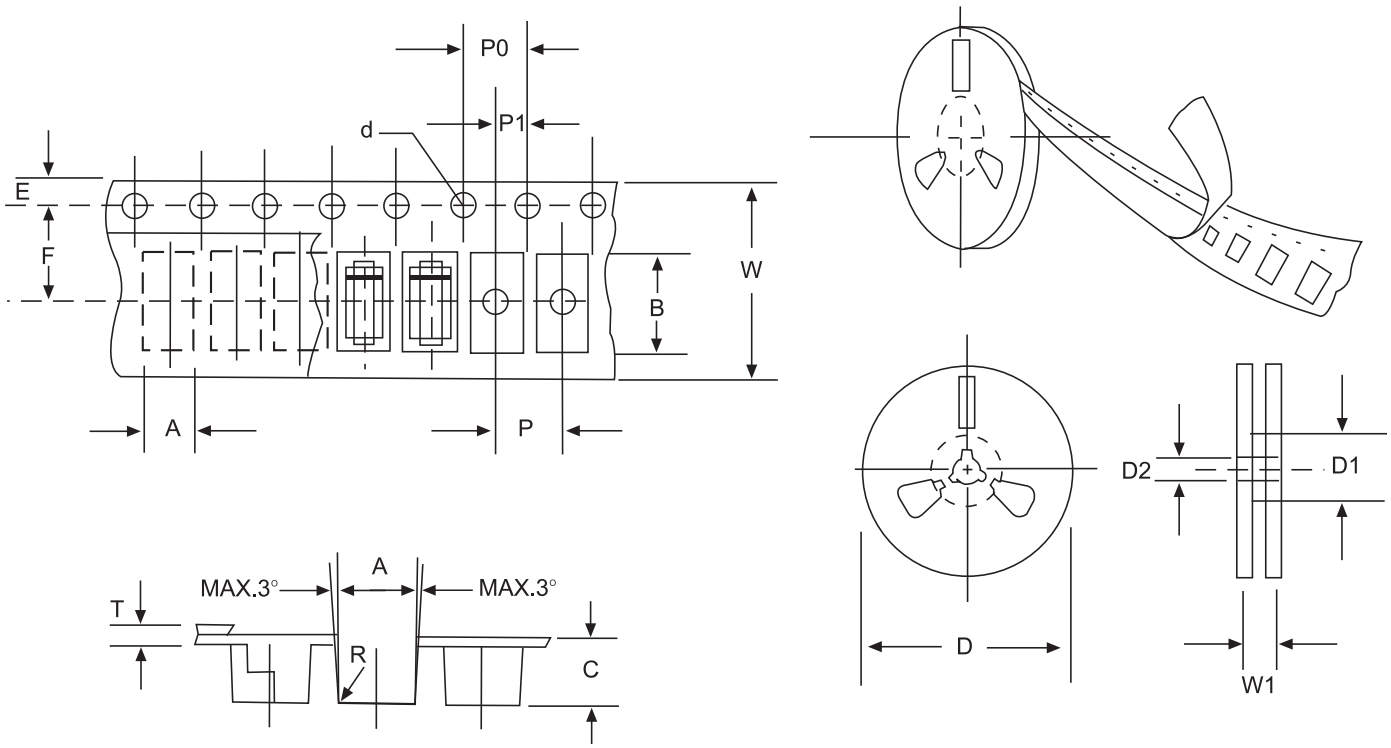


FIG:CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMBG mm(inch)
Carrier width	A	4.09±0.1(0.161±0.004)
Carrier length	B	5.82±0.1(0.229±0.004)
Carrier depth	C	2.50±0.1(0.100±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	330±2.0(13±0.079)
Reel inner diameter	D1	75±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Stroket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.65±0.05(0.222±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.32±0.1 (0.013±0.004)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE:Devices are packed in accordance with EIA standard RS-481-A and specification given above.